

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad	Hole Length
▽	299	6.00mil <0.152mm	PTH	Round	Via	-
☆	16	8.00mil <0.203mm	PTH	Round	Via	-
□	3	21.65mil <0.550mm	NPTH	Slot	Pad	31.50mil <0.800mm
	318 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

REV	ECO	Comments	Date

THIS PCB TO BE MANUFACTURED TO MEET ALL ACCEPTANCE LEVELS OF A CLASS 2 PCB PER ANSI/IPC-A-600G.

MATERIAL: FR-4 or Equivalent
☒ MULTILAYER ☐ 4 LAYERS ☒ CONTROLLED IMPEDANCE
Cu WEIGHT EXTERNAL LAYERS ☐ 0.50Z FINISHED
Cu WEIGHT INTERNAL LAYERS ☐ 10Z FINISHED
FINISHED OVERALL THICKNESS ☐ 0.8 mm ± ☐ 10 %
COPPER THIEVING ALLOWED ☐ YES ☒ NO
VIA TENTING ON BOTH SIDE ☒ YES ☐ NO


FINISH: ☐ LEAD-FREE HOT AIR LEVELING
☒ ENIG
☐ IMMERSION TIN
☐ SMOBC WITH SELECTIVE GOLD PLATING ON LANDS
☐ INDICATED. 1um GOLD OVER 5-10 um NICKEL
SOLDERMASK ☐ DYNACHEM EPIC 200 LPI OR EQUIVALENT
SOLDERMASK COLOR ☐ GREEN HIGH GLOSS
SILKSCREEN COLOR ☐ WHITE

VIAS ARE TENTED IN BOTH SIDE.
ALL HOLES TO BE LOCATED BY THE COORDINATES FROM THE NC DRILL DATA PROVIDED.
USE ARTWORK SET NO. ☐ 05- PCB REV ☐ -

ALL UL LOGO, MANUFACTURER'S ID, AND DATE CODES SHALL BE PLACED ON THE BOTTOM SIDE UNLESS OTHERWISE INDICATED.

ANY ALTERNATIVES TO THE ABOVE SPECIFICATIONS MUST FIRST BE APPROVED.

LAYER STACK-UP		Layer Description	Thickness after Lamination (mils)	Coplanar Waveguide (ohm) +/-10%	Coplanar Waveguide WIDTH/SPACING	DIFF IMP (ohm) +/-10%	DIFF TRACE WIDTH/SPACING	Reference layer
<div>(0.8 +/-0.1mm)</div>		PRIMARY SIDE, SILK SCREEN	0.39					
		PRIMARY SIDE, SOLDER MASK	1.37					
		PRIMARY SIDE, LAYER1(TOP LAYER)	8.66	50	11.9 mils / 6 mils			L2
		DIELECTRIC	1.1					
		INNER PLANE LAYER, LAYER2(GND)	5.1					
		DIELECTRIC	1.1					
		INNER PLANE LAYER, LAYER3(PWR)	8.66					
		DIELECTRIC	1.37					
		SECONDARY SIDE, LAYER4(BOTTOM LAYER)	0.39					
		SECONDARY SIDE, SOLDER MASK						
		SECONDARY SIDE, SILK SCREEN						



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TITLE:
PIC32CX1012BZ25048 Reference Design

PART NUMBER: ☐ -

PCB DESIGNER:
WSG

GERBER FILE:
PIC32CX1012BZ25048 Reference Design

ENGINEER:
WSG

BOARD NUMBER:
-

DOCUMENT NUMBER:

DATE:
10/3/2022

PCB FILE NAME:
PIC32CX1012BZ25048_RD_PCB_AND_ASSEMBLY.dwg

LAYER NAME:
FR4 (4.0mm)

REV:
-

10mm
400mil